

# IR2131

## 3 HIGH SIDE AND 3 LOW SIDE DRIVER

### Features

- Floating channel designed for bootstrap operation  
Fully operational to +600V  
Tolerant to negative transient voltage  
dV/dt immune
- Gate drive supply range from 10 to 20V
- Undervoltage lockout for all channels
- Over-current shutdown turns off all six drivers
- Independent 3 high side & 3 low side drivers
- Matched propagation delay for all channels
- Outputs out of phase with inputs

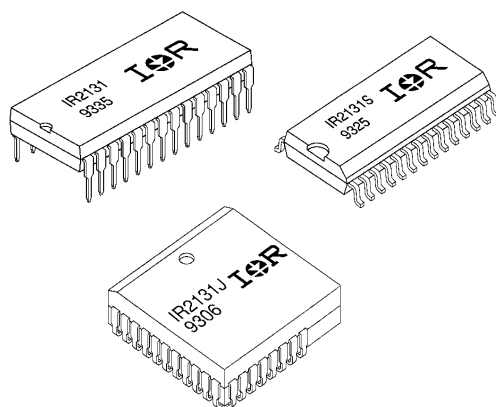
### Description

The IR2131 is a high voltage, high speed power MOSFET and IGBT driver with three independent high and low side referenced output channels. Proprietary HVIC technology enables ruggedized monolithic construction. Logic inputs are compatible with 5V CMOS or LSTTL outputs. A current trip function which terminates all six outputs can be derived from an external current sense resistor. A shutdown input is provided for a customized shutdown function. An open drain FAULT signal is provided to indicate that any of the shutdowns has occurred. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. Propagation delays are matched to simplify use in high frequency applications. The floating channels can be used to drive N-channel power MOSFETs or IGBTs in the high side configuration which operate up to 600 volts.

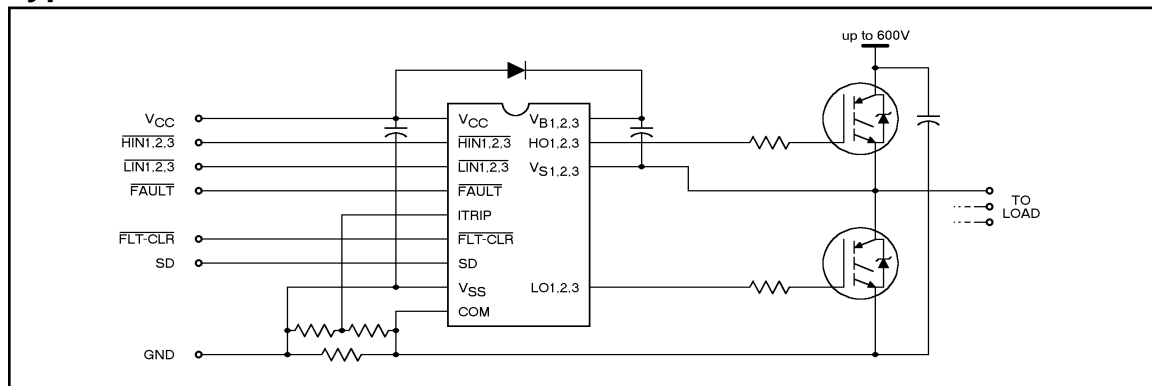
### Product Summary

$V_{\text{OFFSET}}$	600V max.
$I_{\text{O+/-}}$	200 mA / 420 mA
$V_{\text{OUT}}$	10 - 20V
$t_{\text{on/off (typ.)}}$	1.3 & 0.6 $\mu\text{s}$
Deadtime (typ.)	700 ns

### Packages



### Typical Connection



## Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions. Additional Information is shown in Figures 7 through 10.

Symbol	Parameter Definition	Value		Units
		Min.	Max.	
$V_{B1,2,3}$	High Side Floating Supply Voltage	-0.3	525	V
$V_{S1,2,3}$	High Side Floating Offset Voltage	$V_{B1,2,3} - 25$	$V_{B1,2,3} + 0.3$	
$V_{HO1,2,3}$	High Side Floating Output Voltage	$V_{S1,2,3} - 0.3$	$V_{B1,2,3} + 0.3$	
$V_{CC}$	Low Side and Logic Fixed Supply Voltage	-0.3	25	
$V_{SS}$	Logic Ground	$V_{CC} - 25$	$V_{CC} + 0.3$	
$V_{LO1,2,3}$	Low Side Output Voltage	-0.3	$V_{CC} + 0.3$	
$V_{IN}$	Logic Input Voltage (HIN1,2,3, LIN1,2,3, FLT - CLR, SD & ITRIP)	$V_{SS} - 0.3$	$V_{CC} + 0.3$	
$V_{FLT}$	FAULT Output Voltage	$V_{SS} - 0.3$	$V_{CC} + 0.3$	
dV <sub>S</sub> /dt	Allowable Offset Supply Voltage Transient	—	50	V/ns
P <sub>D</sub>	Package Power Dissipation @ T <sub>A</sub> ≤ +25°C (28 Lead DIP)	—	1.5	W
	(28 Lead SOIC)	—	1.6	
	(44 Lead PLCC)	—	2.0	
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient (28 Lead DIP)	—	83	°C/W
	(28 Lead SOIC)	—	78	
	(44 Lead PLCC)	—	63	
T <sub>J</sub>	Junction Temperature	—	150	°C
T <sub>S</sub>	Storage Temperature	-55	150	
T <sub>L</sub>	Lead Temperature (Soldering, 10 seconds)	—	300	

## Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. All voltage parameters are absolute voltages referenced to COM. The V<sub>S</sub> offset rating is tested with all supplies biased at 15V differential.

Symbol	Parameter Definition	Value		Units
		Min.	Max.	
$V_{B1,2,3}$	High Side Floating Supply Voltage	$V_{S1,2,3} + 10$	$V_{S1,2,3} + 20$	V
$V_{S1,2,3}$	High Side Floating Offset Voltage	Note 1	600	
$V_{HO1,2,3}$	High Side Floating Output Voltage	$V_{S1,2,3}$	$V_{B1,2,3}$	
$V_{CC}$	Low Side and Logic Fixed Supply Voltage	10	20	
$V_{SS}$	Logic Ground	-5	5	
$V_{LO1,2,3}$	Low Side Output Voltage	0	$V_{CC}$	
$V_{IN}$	Logic Input Voltage (HIN1,2,3, LIN1,2,3, FLT - CLR, SD & ITRIP)	$V_{SS}$	$V_{SS} + 5$	
$V_{FLT}$	FAULT Output Voltage	$V_{SS}$	$V_{CC}$	
T <sub>A</sub>	Ambient Temperature	-40	125	°C

Note 1: Logic operational for V<sub>S</sub> of -5V to +600V. Logic state held for V<sub>S</sub> of -5V to -V<sub>BS</sub>.

## Dynamic Electrical Characteristics

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS1,2,3}$ ) = 15V,  $V_{S1,2,3}$  =  $V_{SS}$  = COM,  $C_L$  = 1000 pF and  $T_A$  = 25°C unless otherwise specified. The dynamic electrical characteristics are defined in Figures 4 through 5.

Symbol	Parameter Definition	Value			Units	Test Conditions
		Min.	Typ.	Max.		
$t_{on}$	Turn-On Propagation Delay	0.6	1.3	2.0	$\mu s$	$V_{IN} = 0$ & 5V $V_{S1,2,3} = 0$ to 600V
$t_{off}$	Turn-Off Propagation Delay	0.2	0.6	1.0		
$t_r$	Turn-On Rise Time	—	80	150		
$t_f$	Turn-Off Fall Time	—	40	100		
$t_{itrip}$	ITRIP to Output Shutdown Propagation Delay	400	700	1000	ns	$V_{IN}$ , $V_{ITRIP} = 0$ & 5V
$t_{bl}$	ITRIP Blanking Time	—	400	—		$V_{ITRIP} = 1V$
$t_{flt}$	ITRIP to FAULT Indication Delay	400	700	1000		$V_{IN}$ , $V_{ITRIP} = 0$ & 5V
$t_{flt,in}$	Input Filter Time (All Six Inputs)	—	310	—		$V_{IN} = 0$ & 5V
$t_{fltclr}$	FLT-CLR to FAULT Clear Time	400	700	1000		$V_{IN}$ , $V_{IT}$ , $V_{FC} = 0$ & 5V
$t_{sd}$	SD to Output Shutdown Propagation Delay	400	700	1000		$V_{IN}$ , $V_{SD} = 0$ & 5V
DT	Deadtime	400	700	1200		$V_{IN} = 0$ & 5V

## Static Electrical Characteristics

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS1,2,3}$ ) = 15V,  $V_{S1,2,3}$  =  $V_{SS}$  = COM and  $T_A$  = 25°C unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}$  and are applicable to all six logic input leads: HIN1,2,3 & LIN1,2,3. The  $V_O$  and  $I_O$  parameters are referenced to COM and  $V_{S1,2,3}$  and are applicable to the respective output leads: HO1,2,3 or LO1,2,3.

Symbol	Parameter Definition	Value			Units	Test Conditions
		Min.	Typ.	Max.		
$V_{IH}$	Logic "0" Input Voltage (OUT = LO)	2.2	—	—	V	
$V_{IL}$	Logic "1" Input Voltage (OUT = HI)	—	—	0.8		
$V_{FCLR,IH}$	Logic "0" Fault Clear Input Voltage	2.2	—	—		
$V_{FCLR,IL}$	Logic "1" Fault Clear Input Voltage	—	—	0.8		
$V_{SD,TH+}$	Shutdown Input Positive Going Threshold	1.2	1.8	2.1		
$V_{SD,TH-}$	Shutdown Input Negative Going Threshold	0.9	1.5	1.8		
$V_{IT,TH+}$	ITRIP Input Positive Going Threshold	250	485	600	mV	
$V_{IT,TH-}$	ITRIP Input Negative Going Threshold	200	400	550		
$V_{OH}$	High Level Output Voltage, $V_{BIAS} - V_O$	—	—	100		$V_{IN} = 0V$ , $I_O = 0A$
$V_{OL}$	Low Level Output Voltage, $V_O$	—	—	100		$V_{IN} = 5V$ , $I_O = 0A$
$I_{LK}$	Offset Supply Leakage Current	—	—	50	$\mu A$	$V_B = V_S = 600V$
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	—	30	100	$\mu A$	$V_{IN} = 0V$ or 5V
$I_{QCC}$	Quiescent $V_{CC}$ Supply Current	—	3.0	4.5	mA	$V_{IN} = 0V$ or 5V
$I_{IN+}$	Logic "1" Input Bias Current (OUT = HI)	—	190	300	$\mu A$	$V_{IN} = 0V$
$I_{IN-}$	Logic "0" Input Bias Current (OUT = LO)	—	50	100		$V_{IN} = 5V$
$I_{ITRIP+}$	"High" ITRIP Bias Current	—	75	150		ITRIP = 5V
$I_{ITRIP-}$	"Low" ITRIP Bias Current	—	—	100	nA	ITRIP = 0V
$I_{FCLR+}$	Logic "1" Fault Clear Bias Current	—	125	250	$\mu A$	FLT-CLR = 0V
$I_{FCLR-}$	Logic "0" Fault Clear Bias Current	—	75	150		FLT-CLR = 5V
$I_{SD+}$	Logic "1" Shutdown Bias Current	—	75	150		SD = 5V
$I_{SD-}$	Logic "0" Shutdown Bias Current	—	—	100		SD = 0V

# IR2131

## Static Electrical Characteristics -- Continued

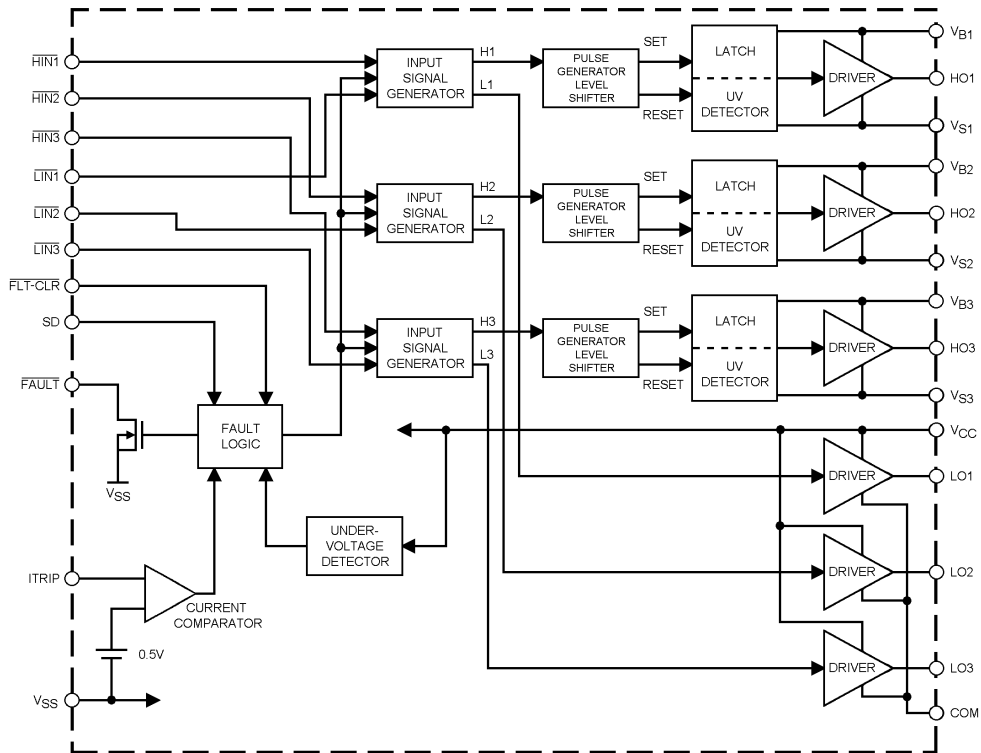
$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS1,2,3}$ ) = 15V,  $V_{S1,2,3} = V_{SS} = COM$  and  $T_A = 25^\circ C$  unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}$  and are applicable to all six logic input leads:  $HIN1,2,3$  &  $LIN1,2,3$ . The  $V_O$  and  $I_O$  parameters are referenced to  $COM$  and  $V_{S1,2,3}$  and are applicable to the respective output leads:  $HO1,2,3$  or  $LO1,2,3$ .

Symbol	Parameter Definition	Value			Units	Test Conditions
		Min.	Typ.	Max.		
$V_{BSUV+}$	$V_{BS}$ Supply Undervoltage Positive Going Threshold	8.2	8.7	9.2	V	
$V_{BSUV-}$	$V_{BS}$ Supply Undervoltage Negative Going Threshold	7.8	8.3	8.8		
$V_{CCUV+}$	$V_{CC}$ Supply Undervoltage Positive Going Threshold	8.2	8.7	9.2		
$V_{CCUV-}$	$V_{CC}$ Supply Undervoltage Negative Going Threshold	7.8	8.3	8.8		
$R_{on,FLT}$	$\overline{FAULT}$ Low On-Resistance	—	55	75	$\Omega$	
$I_{O+}$	Output High Short Circuit Pulsed Current	200	250	—	mA	$V_O = 0V, V_{IN} = 0V$ $PW \leq 10 \mu s$
$I_{O-}$	Output Low Short Circuit Pulsed Current	420	500	—		$V_O = 15V, V_{IN} = 5V$ $PW \leq 10 \mu s$

## Lead Assignments

<p>28 Lead DIP</p>	<p>44 Lead PLCC w/o 12 Leads</p>	<p>28 Lead SOIC (Wide Body)</p>
<b>IR2131</b>	<b>IR2131J</b>	<b>IR2131S</b>
<b>Part Number</b>		

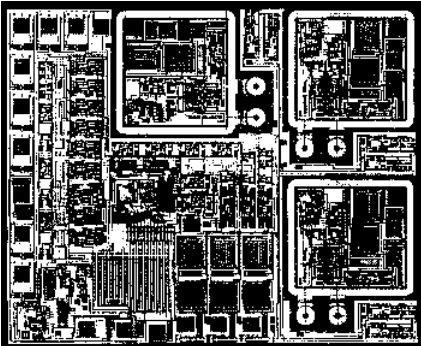
## Functional Block Diagram

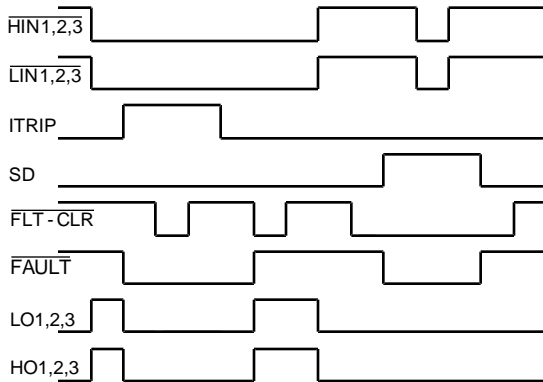


## Lead Definitions

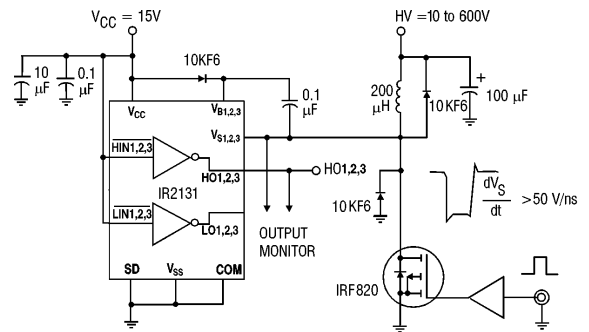
Lead	
Symbol	Description
HIN1,2,3	Logic inputs for high side gate driver outputs (HO1,2,3), out of phase
LIN1,2,3	Logic inputs for low side gate driver output (LO1,2,3), out of phase
FLT-CLR	Logic input for fault clear
SD	Logic input for shutdown
FAULT	Indicates over-current or undervoltage lockout (low side) has occurred, negative logic
VCC	Low side and logic fixed supply
ITRIP	Input for over-current shutdown
VSS	Logic ground
Vb1,2,3	High side floating supplies
HO1,2,3	High side gate drive outputs
Vs1,2,3	High side floating supply returns
LO1,2,3	Low side gate drive outputs
COM	Low side return

## Device Information

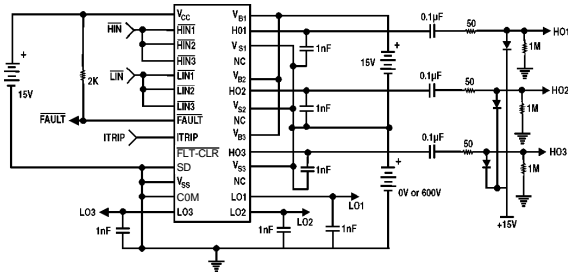
Process & Design Rule		HVDCMOS 4.0 $\mu\text{m}$	
Transistor Count		700	
Die Size		167 X 141 X 26 (mil)	
Die Outline			
Thickness of Gate Oxide		800Å	
Connections	First Layer	Material	Poly Silicon
		Width	4 $\mu\text{m}$
		Spacing	6 $\mu\text{m}$
		Thickness	5000Å
	Second Layer	Material	Al - Si (Si: 1.0% $\pm$ 0.1%)
		Width	6 $\mu\text{m}$
		Spacing	9 $\mu\text{m}$
		Thickness	20,000Å
	Contact Hole Dimension		8 $\mu\text{m}$ X 8 $\mu\text{m}$
	Insulation Layer	Material	PSG ( $\text{SiO}_2$ )
		Thickness	1.5 $\mu\text{m}$
Passivation	Material		PSG ( $\text{SiO}_2$ )
	Thickness		1.5 $\mu\text{m}$
Method of Saw		Full Cut	
Method of Die Bond		Ablebond 84 - 1	
Wire Bond	Method		Thermo Sonic
	Material		Au (1.0 mil / 1.3 mil)
Leadframe	Material		Cu
	Die Area		Ag
	Lead Plating		Pb : Sn (37 : 63)
Package	Types		28 Lead PDIP & SOIC / 44 Lead PLCC
	Materials		EME6300 / MP150 / MP190
Remarks:			



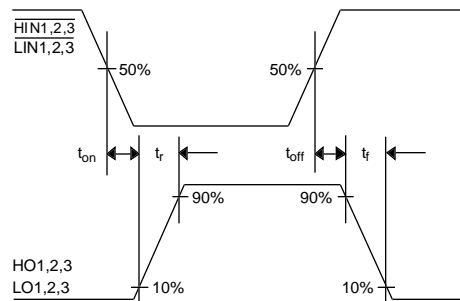
**Figure 1. Input/Output Timing Diagram**



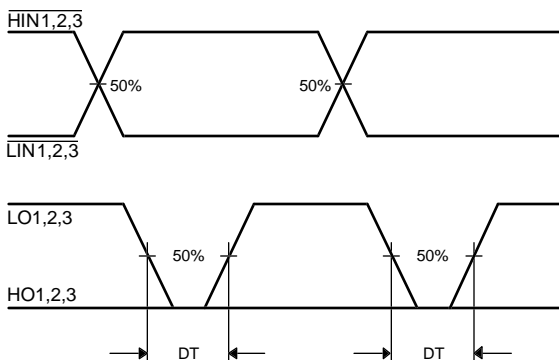
**Figure 2. Floating Supply Voltage Transient Test Circuit**



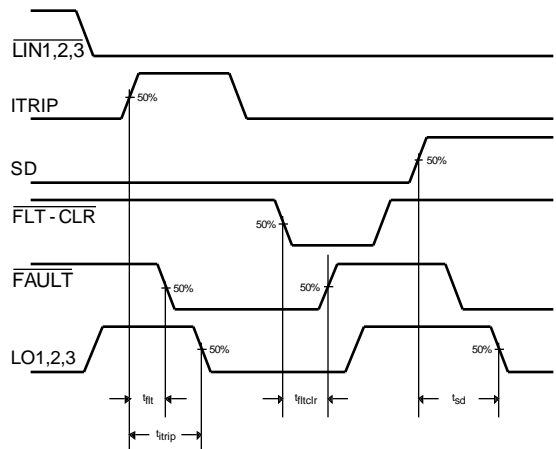
**Figure 3. Switching Time Test Circuit**



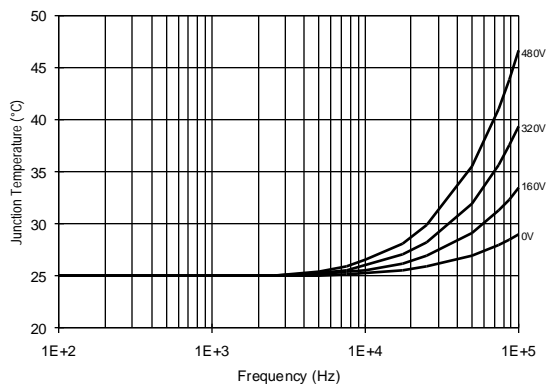
**Figure 4. Switching Time Waveform Definitions**



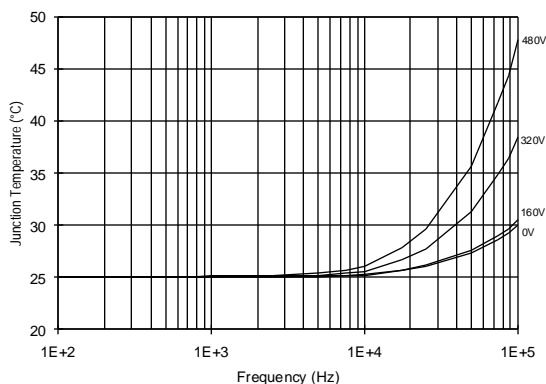
**Figure 5. Deadtime Waveform Definitions**



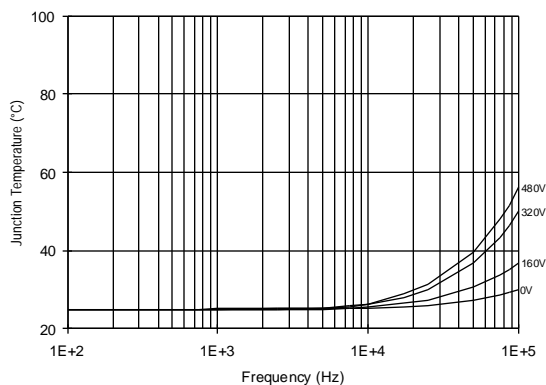
**Figure 6. Shutdown Waveform Definitions**



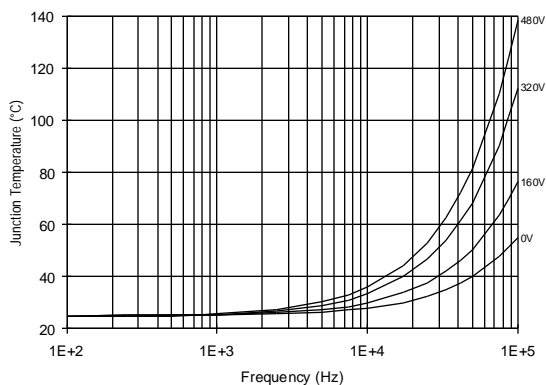
**Figure 7. IR2131  $T_j$  vs. Frequency (IRF820)**  
 $R_{GATE} = 33\Omega$ ,  $V_{CC} = 15\text{V}$



**Figure 8. IR2131  $T_j$  vs. Frequency (IRF830)**  
 $R_{GATE} = 20\Omega$ ,  $V_{CC} = 15\text{V}$



**Figure 9. IR2131  $T_j$  vs. Frequency (IRF840)**  
 $R_{GATE} = 15\Omega$ ,  $V_{CC} = 15\text{V}$



**Figure 10. IR2131  $T_j$  vs. Frequency (IRF450)**  
 $R_{GATE} = 10\Omega$ ,  $V_{CC} = 15\text{V}$